PROTOTYPING

830-Point Solderless Breadboard

A 830-point full-size solderless breadboard lets you build and test circuits without soldering. Push component legs and jumper wires into the holes and they connect through spring clips inside. It has 830 tie points, power rails on both sides and an adhesive back. It is the first tool every electronics learner needs.



Key Features

- 830 tie points (630 terminal + 200 power-rail points)
- Standard 2.54 mm (0.1") hole pitch, so it fits DIP ICs and header pins
- Red (+) and blue (−) power rails on both sides
- Reusable nickel-plated phosphor-bronze spring contacts
- Self-adhesive back for mounting

Technical Specifications

Tie points	830
Terminal strips	63 rows × 2 groups of 5 (a–e, f–j)
Power rails	2 pairs (one on each side)
Hole pitch	2.54 mm
Wire size	20–29 AWG (0.3–0.8 mm)
Body material	ABS plastic
Typical rating	300 V, 3–5 A
Size (approx.)	165 × 55 mm

Pinout / Connections

Rows a–e	5 holes in a row are connected
Rows f–j	5 holes in a row are connected
Centre gap	Straddle DIP ICs across this gap
Rails + / −	Run lengthwise for power and ground

Typical Applications

- Prototyping Arduino and sensor circuits
- School and lab experiments
- Testing ICs and modules before soldering

Usage Notes & Safety

! On some boards the power rails are split in the middle. Check with a multimeter or bridge them with a wire.

! Don't force thick component leads into the holes. It loosens the clips.

! Low-voltage DC use only. Never use a breadboard for mains (230 V AC).